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APPLICATION NO.	, I	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/502,117	•	07/21/2004	Akihiko Okubora	075834.00270	2114	
33448	7590	03/07/2006		EXAM	EXAMINER	
ROBERT J. DEPKE			DINH, TUAN T			
LEWIS T. S				ART UNIT	PAPER NUMBER	
TREXLER,	BUSHNI	ELL, GLANGLO	RGI, BLACKSTONE & MARR	AKTONII	PAFER NOMBER	
105 WEST A	ADAMS	STREET, SUITI	E 3600	2841		
CHICAGO,	IL 6060	03-6299		DATE MAIL ED. 02/07/200		

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Please find below and/or attached an Office communication concerning this application or proceeding.

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•		Application No.	Applicant(s)	
		10/502,117	OKUBORA, AKIHIKO	
	Office Action Summary	Examiner	Art Unit	
		Tuan T. Dinh	2841	
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet v	vith the correspondence address	
WHIC - Exter after - If NO - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DANSIONS OF TIME MAY BE AVAILABLE OF THE MAILING DANSIONS OF THE MAILING DANSIONS OF THE MAILING DANSIONS OF THE MAILING DANSIONS OF THE MAILING THE MAI	ATE OF THIS COMMUN 36(a). In no event, however, may a vill apply and will expire SIX (6) MC , cause the application to become A	ICATION. reply be timely filed PNTHS from the mailing date of this communication ABANDONED (35 U.S.C. § 133).	
Status				
2a)⊠	Responsive to communication(s) filed on 30 Second This action is FINAL . 2b) This Since this application is in condition for allower closed in accordance with the practice under Exercise 1.00 Second This Secon	action is non-final. nce except for formal ma		S
Dispositi	on of Claims			
5)□ 6)⊠ 7)□ 8)□	Claim(s) 1-3,5-9,11-14,16 and 17 is/are pending 4a) Of the above claim(s) is/are withdraw Claim(s) is/are allowed. Claim(s) 1-3,5-9,11-14,16 and 17 is/are rejected Claim(s) is/are objected to. Claim(s) are subject to restriction and/or on Papers	vn from consideration.		
10)⊠	The specification is objected to by the Examine The drawing(s) filed on 30 September 2005 is/a Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction to the other contents of the oath or declaration is objected to by the Example 1.	are: a) ☐ accepted or b) drawing(s) be held in abeya ion is required if the drawin	ance. See 37 CFR 1.85(a). g(s) is objected to. See 37 CFR 1.121(c	러).
Priority u	ınder 35 U.S.C. § 119			
a)[Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority application from the International Bureau see the attached detailed Office action for a list of	s have been received. s have been received in a ity documents have been (PCT Rule 17.2(a)).	Application No n received in this National Stage	
2) 🔲 Notice 3) 🔲 Inforn	(s) e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) No(s)/Mail Date	Paper No	Summary (PTO-413) (s)/Mail Date Informal Patent Application (PTO-152)	

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DETAILED ACTION

Claim Rejections - 35 USC § 112

1. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

- 2. Claim 17 is recites the limitation "the grounding layers" in line 11. There is insufficient antecedent basis for this limitation in the claim.
- 3. Claim 17 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claim 17, lines 10-11, it is unclear because the phrase of "wherein...beyond either of the grounding layers" is not understood and not completed.

By applying art, examiner assumes that that phrase should be read as "wherein... beyond the grounding layer."

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section

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351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

5. Claims 1-3 are rejected under 35 U.S.C. 102(e) as being anticipated by Kubota et al. (U.S. Patent 6,183,669).

As to claims 1, 3, Kubota et al. discloses a high-frequency module (1, column 12, line 1) as shown in figure 1 including a wiring pattern (5, column 12, line 5) formed in an organic insulative layer (2, 3) and a plurality of conductive parts (capacitor C, Inductor L, and resistor 11, column 12, lines 3-7) forming passive elements and distributed parameter elements (strip lines, column 12, line 4), which transmit a high-frequency signal, each of the conductive parts being formed correspondingly to an area of the organic insulative layer where no woven glass fabric is laid, and the organic insulative layer is formed from any one of these organic materials having a ceramic powder dispersed therein (column 3, lines 11-15, 39-40, column 4, lines 56-60, and many place in a detailed description, start at column 5).

As to claim 2, Kubota et al. discloses each of the conductive parts (C, I, R, and strip lines) is covered with a ground layer (5) formed on the organic insulative layer to form a strip structure or a micro-strip structure.

6. Claims 5-6, 8-9, and 11-12, and 14 are rejected under 35 U.S.C. 102(b) as being anticipated by Geller et al. (U.S. Patent 5,929,510).

As to claim 5, 9, and 11, Geller et al. discloses a high-frequency module (10, column 2, line 10) and a method of producing a high frequency module (10) as shown in figure 1 comprising:

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a base substrate block (16, 30, column 2, lines 15-16, 29-30) comprising an organic substrate, and having a plurality of wiring layers each including an organic insulative layer (18, 32, column 2, lines 17-18, 31-32) and a wiring pattern (22, column 2, lines 19-20) and having at least the uppermost one of the wiring layers (36) layer flattened to form a buildup surface (a surface on top portion 16 and 30), and

an elements block (40, and 42) having formed in the organic insulative layer (the insulative layer 40, and 42) formed on the main side of the buildup surface of the base substrate block (16, and 30) a wiring pattern (44, 46, 48, 50) and a plurality of conductive parts (62, 64, and 66, which are a resistor or capacitor, see column 2, lines 49-50) forming passive elements and distributed parameter elements (strip lines 44, 46, 48, 50, 52, 54, 56, 58, and 60), which transmit a high-frequency signal,

each of the conductive parts (components and strip lines) of the elements block (30, 40, and 42) is formed correspondingly to an area of the organic insulative layer where no woven glass fabric is laid; and

the organic substrate (16, 30) and organic insulative layer (18, 32, 40, and 42) are formed from any one of these organic materials having a ceramic powder dispersed therein (see column 2, lines 14-15).

As to claims 6, 12, Geller et al. discloses the base substrate block (16, 30) has a ground pattern (36, column 3, lines 1-10) in a portion of the organic insulative layer (32) corresponding to the conductive parts and no woven glass fabric is laid at least between the ground pattern and conductive parts.

As to claims 8, 14, Geller et al. discloses the wiring layers (22, 24) in the base substrate block (16, 30) have no woven glass fabric formed in portions thereof opposite to areas where the conductive parts (cap, resistor, or strip lines) are formed.

Claim Rejections - 35 USC § 103

- 7. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 8. Claims 7, 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Geller et al. ('510) in view of Kamimura et al. (U.S. Patent 5,373,112).

Geller et al. does not disclose shielded by a ground pattern formed on the organic insulative layer to enclose the perimeters of the conductive parts, the conductive parts formed together a strip structure or a micro-strip structure.

Kamimura et al. shows a multilayer wiring board as shown in figures 1-3 comprising a ground layer (12, 13, column 4, lines 53-56) being shielded and enclosed the perimeters of conductive parts (1, capacitors), the conductive parts formed a strip structure

It would have been obvious to one having ordinary skill in the art at the time the invention was made to have a ground being shield and enclosed conductive parts and the conductive parts formed a strip structure as taught by Kamimura et al, employ in the module of Geller in order to perform a grounding, and suppress noise.

9. Claims 16-17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Geller et al. ('510) in view of Prior Art (figure 5, submitted by applicant, hereafter PA).

Regarding claim 16, Geller et al. discloses all of the limitation of the claimed invention (see claim 5), except for the organic substrate containing a woven glass fiber.

PA-figure 5 teaches a high frequency module (140) comprising an organic substrate (143) containing a woven glass fiber.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to use a woven glass fiber as taught by PA, employed in the module of Geller in order to perform an excellent heat dissipation.

Regarding claim 17, Geller et al. discloses two organic substrate (40, 42 and 16), and all of the limitation as disclosed in claims 5 and 6. However, Geller et al. does not disclose the substrate containing a woven glass fiber.

PA-figure 5 teach two organic substrate (143, 144) containing woven glass fiber.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to use woven glass fibers containing in the substrates as taught by PA, employed in the module of Geller in order to perform excellent heat dissipations.

Response to Arguments

10. Applicant's arguments with respect to claims1-3, 5-9,11-14, and 16-17 have been considered but are most in view of the new ground(s) of rejection.

Applicant argues:

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Either Kubota ('669) and Geller et al. ('510) does not disclose the organic insulative having a ceramic power dispersed thereon.

Examiner disagrees.

Kubota ('669) discloses ceramic green sheets containing a ceramic powder, see column 3, lines 11-15, 39-40, column 4, lines 56-60).

Geller et al. ('510) discloses a insulative layer containing a ceramic powder, see column 2, lines 12-17.

For as reason as above, examiner believes two references cited do disclose all of the limitation of the claimed invention. Therefore, Kubota and Geller are proper rejected under U.S.C 102 rejection.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of

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the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Tuan Dịnh June 24, 2005.